

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 GHK.	査閲 APPD.	承認 APPD.
2	10.Feb.2006	059307	CORRECTION OF ERROR IN WRITING	E.MURANO	Y.YAHIRO		K.Hidolawa

DESIGNATION

MM50-200B\*-E1RE

SERIES PREFIX  
シリーズ名

NO. OF CONTACTS  
芯数

SOCKET TYPE  
ソケットタイプ  
B: LATCH TYPE SMT

CONTACT FINISH  
接点仕上げ  
1: Au (0.1µm MIN) OVER NI  
R: REVERSE  
NONE: STANDARD

MODIFY CODE  
モディファイコード  
E: 6.5mm HEIGHT

KEYING TYPE (DETAIL A) 2: TYPE B (1.8V)  
キタイプ  
1: TYPE A (2.5V)

APPLICABLE DIMM (REF.)

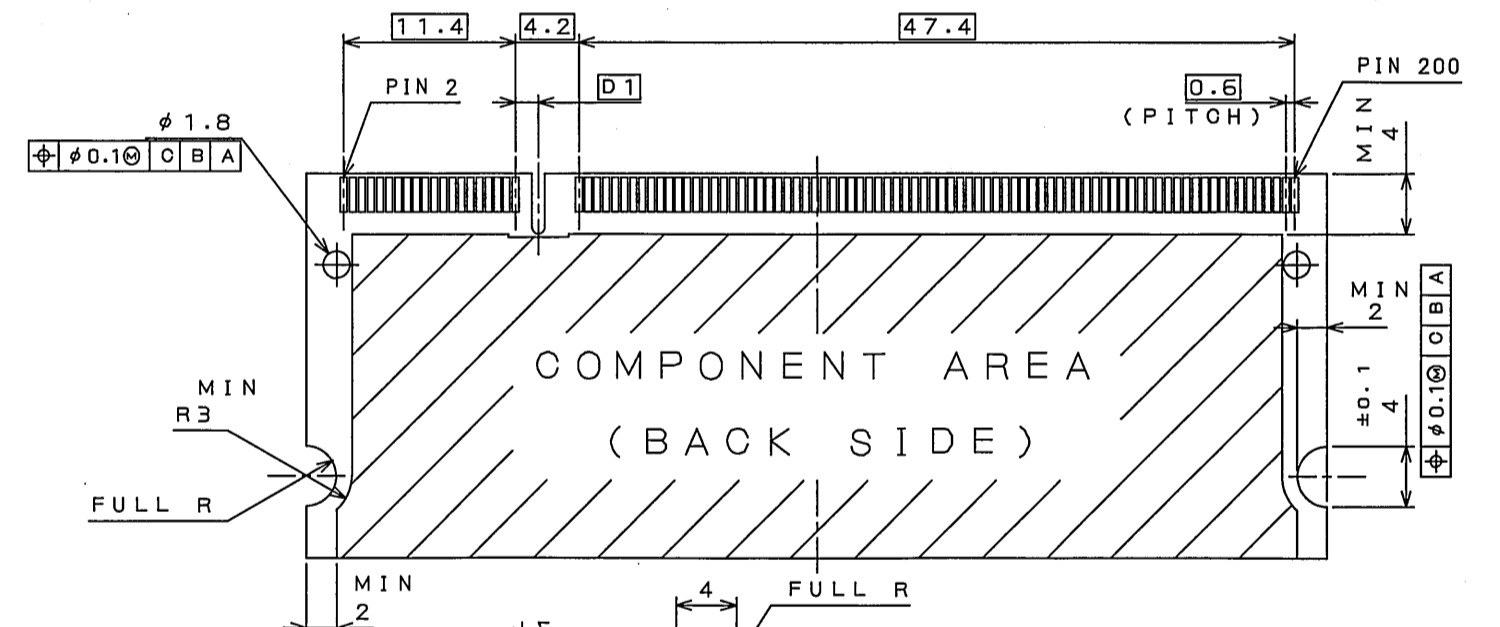
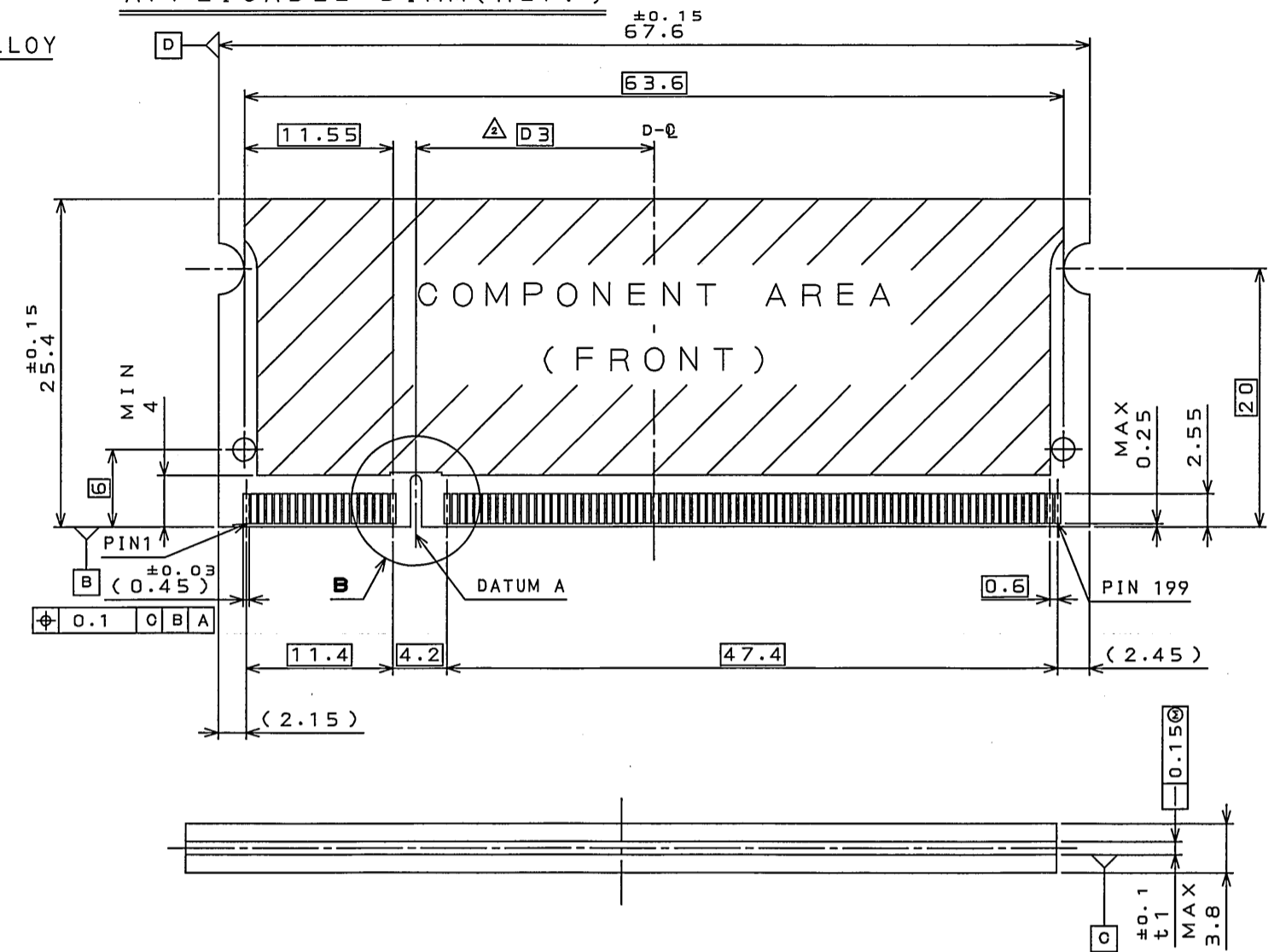


TABLE 1  
MECHANICAL KEYING

POWER SPPLY	D1	D2	D3
2.5V (TYPE A)	1.5	1.8	18.45
1.8V (TYPE B)	2.4	2.7	17.55

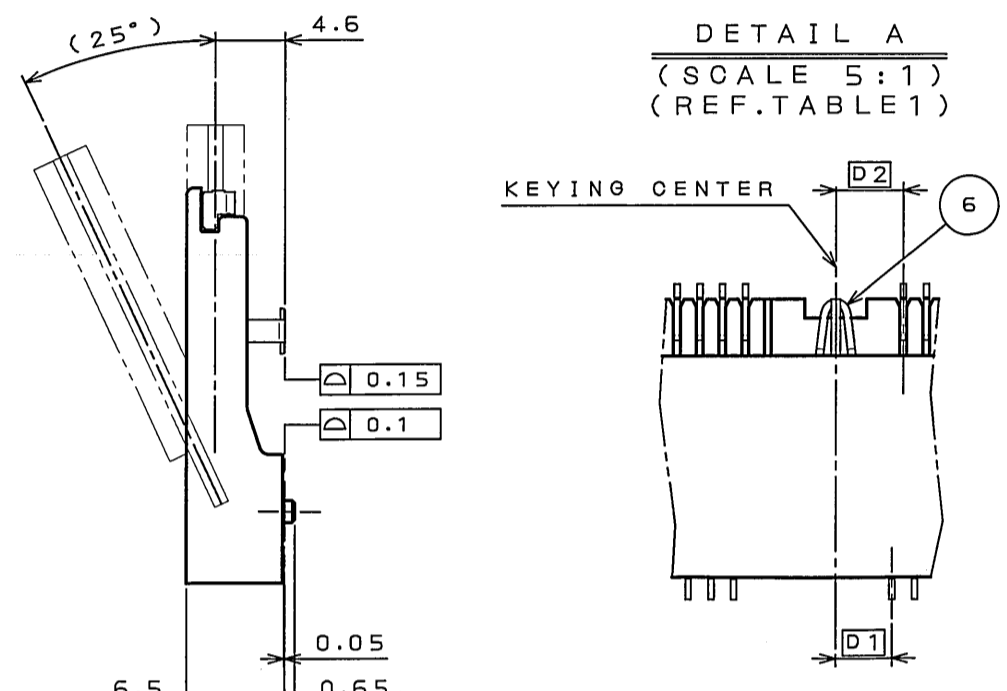
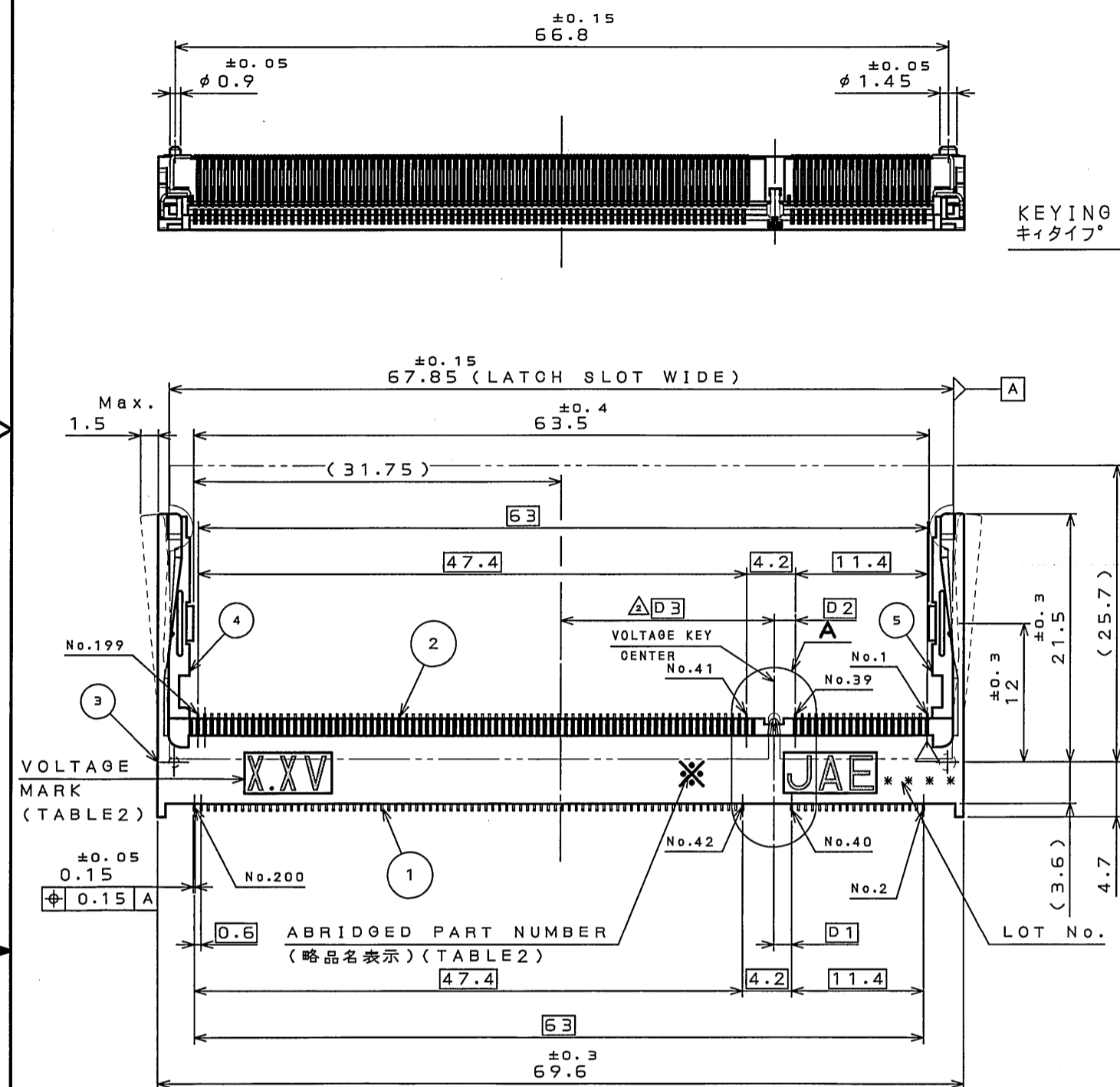
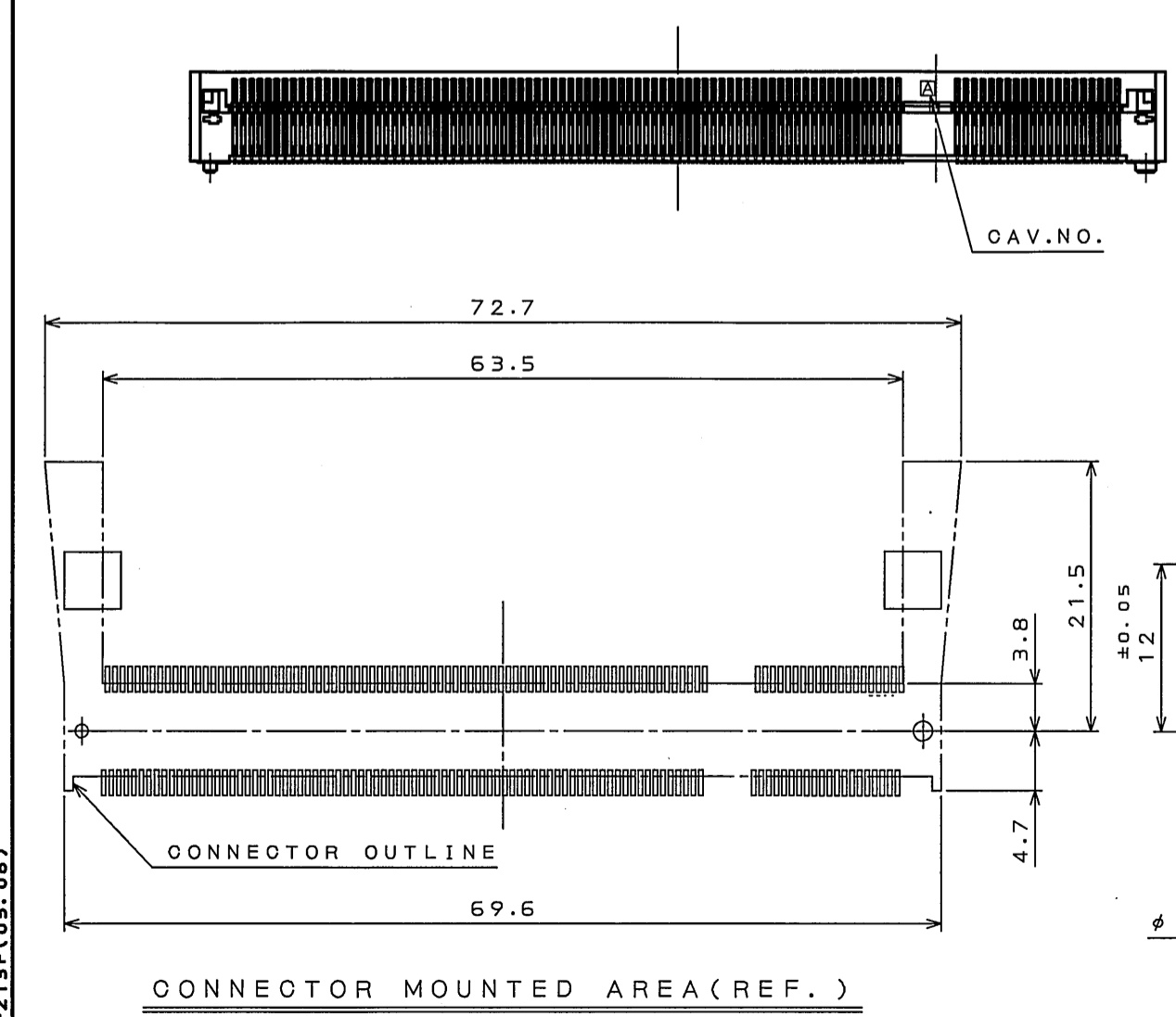
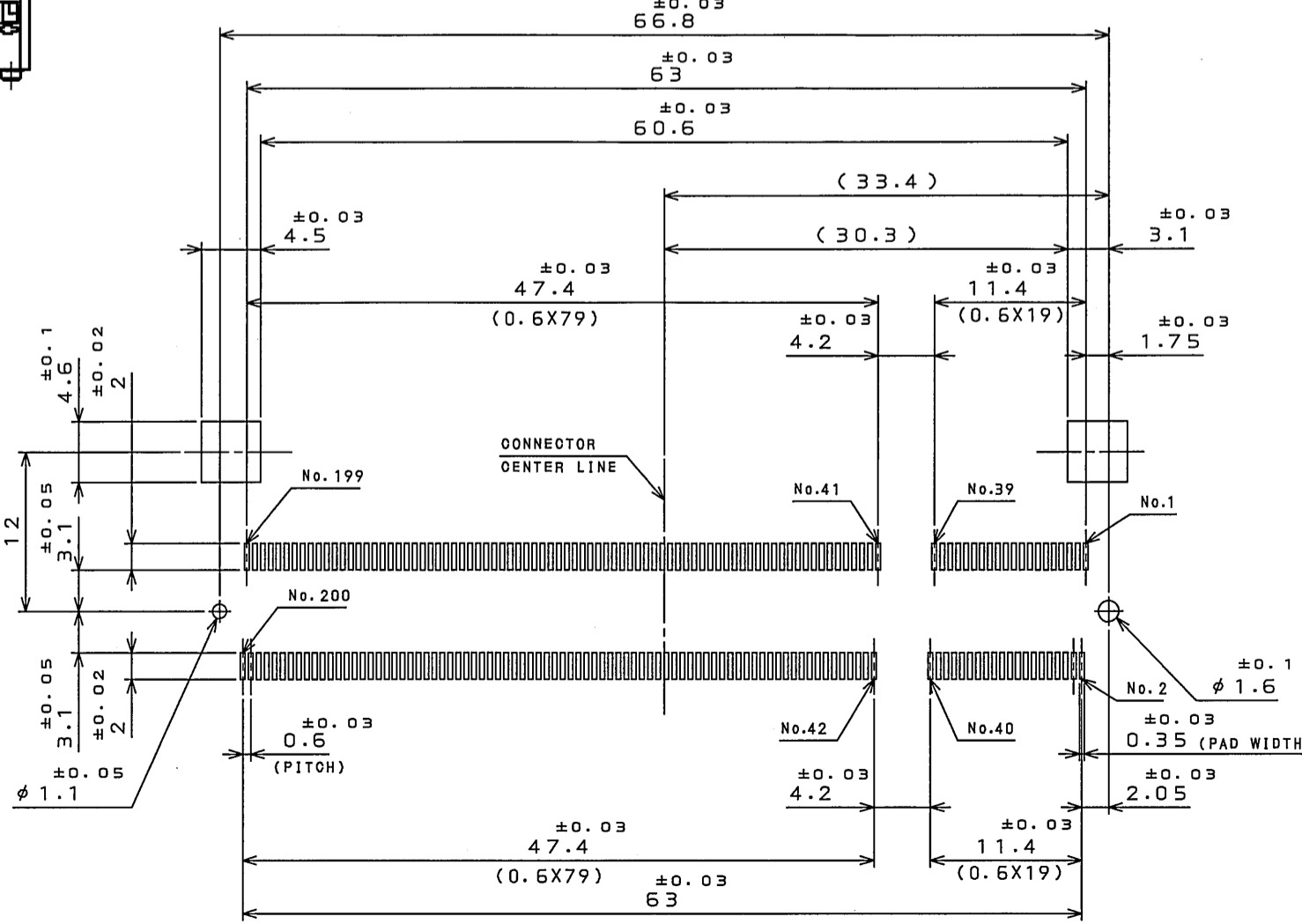


TABLE 2  
DISCRIMINATION MARK

PARTS NAME	VOLTAGE MARK	ABRIDGED PART NUMBER
MM50-200B1-E1RE	2.5V	E1RE
MM50-200B2-E1RE	1.8V	2-E1RE

APPLICABLE P.C.B. DIMENSION (REF.)  
 適合基板寸法 (参考)



6 KEY	1 STAINLESS		
5 HOLD DOWN 2	1 PHOSPHOR BRONZE TIN PLATING		
4 HOLD DOWN 1	1 PHOSPHOR BRONZE TIN PLATING		
3 INSULATOR	1 GLASS FILLED LOP		UL94 V-0 COLOR WHITE
2 BOTTOM SIDE CONTACT	100 PHOSPHOR BRONZE	CONTACT AREA: Au (0.1µm MIN) OVER NI SOLDERING AREA: GOLD FLASH OVER NI	
1 TOP SIDE CONTACT	100 PHOSPHOR BRONZE	CONTACT AREA: Au (0.1µm MIN) OVER NI SOLDERING AREA: GOLD FLASH OVER NI	

符号 NO. 名称 DESCRIPTION 個数 QTY. 材料 MATERIAL 仕上 FINISH 備考 REMARKS

仕様書 (SPECIFICATION) JACS-1655-01 第1版 (ORIGINAL DATE) 20.May.2004 尺度 (SCALE) 2:1 シリーズ (SERIES) MM50 日本航空電子工業株式会社

一般公差 (GENERAL TOLERANCE) 寸法 (DIMENSION) 角度 (ANGLES)

製造 DR. 担当 GHK. 査閲 APPD. 承認 APPD.

R.KATOU  
Y.YAHIRO  
S.KASHIWA01

名称 (TITLE) MM50  
-200B\*-E1RE 日本航空電子工業株式会社  
ELECTRONICS  
INDUSTRY, LTD.

図面番号 (DRAWING NO.) SJ101278 版数 (REV.) 2

DOF-0-213F(05.08)

